ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INTERNATION CONNECTING	nposition De 5. IPC, Bannockt Pan-American co	c laration ourn, Illinois. A opyright conve	All rights reserved untions.	nder both	This docume level parts, t	ent is a declaration en declaration	on of the substan	ces within the ma wer level materia	nufacturer list als for which th	ed item. Note: i ne manufacture	if the item is an as r has engineering	ssembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				s Materials and	als and Mfg Information			
upplier Information													
ompany name*	Company unique ID			1	Unique ID Authority				Response Date*				
nsemi									2024-04-27				
Contact Name Title - Contact			t F		Phone - Contact*			Ema	Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative* Tit			Title - Representative			Phone - Representative*			Ema	Email - Representative*			
roduct-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Iter		n Number Mfr Item Name				Effective Date	Version	Manufacturing	g Site	Weight*	UOM	Unit Type	
	MC78M	MC78M05ABTG ANA 500MA 5		VREG		2024-04-27		MY1		1365.61	mg	Each	
Ianufacturing Proccess Inform	nation												
Terminal Plating / Grid Array	Terminal Plating / Grid Array Material Terminal Base		lloy J-STD-020 MSL Rating		L Rating	Peak Process Body Temperature Max Time		at Peak Temp	eak Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed		CU Alloy	U Alloy NA			0 C		30	se	conds 3			
omments													
or more information regarding mater	ial composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	1.61	mg	Supplier	Silicon (Si)	7440-21-3		1.61	mg	
Die Attach	0.21	mg	А	Lead (Pb)	7439-92-1	7a	0.1995	mg	
			Supplier	Tin (Sn)	7440-31-5		0.0105	mg	
Lead Frame	677.24	mg	В	Nickel (Ni)	7440-02-0		0.3386	mg	
			Supplier	Iron (Fe)	7439-89-6		0.6772	mg	
			Supplier	Copper (Cu)	7440-50-8		676.0209	mg	
			Supplier	Phosphorus (P)	7723-14-0		0.2032	mg	
Mold Compound-Black	644.0	mg		Phenolic Resin	proprietary data		38.64	mg	
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		64.4	mg	
			Supplier	Carbon Black (C)	1333-86-4		3.22	mg	
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		48.3	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		489.44	mg	
Plating	42.4	mg	Supplier	Tin (Sn)	7440-31-5		42.4	mg	
Wire Bond - Cu	0.15	mg	Supplier	Copper (Cu)	7440-50-8		0.15	mg	

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3